



NOTES:

1. HOUSING MATERIAL: THERMOPLASTIC POLYESTER UL94V-0 BALCK; TERMINAL MATERIAL: COPPER ALLOY
2. FINISHED: GOLD PATING IN CONTACT AREA, TIN PLATING IN SOLDER AREA,NICKEL UNDERPLATING OVER ALL.
3. CONNECTOR MARKED WITH PART NUMBER AND DATE CODE.
4. VOLTAGE:
POWER CONTACT: 250 VOLTS
5. CURRENT
POWER CONTACT:40A,PER MATED CONTACT,
POWER CONTACT CURRENT INTERRUPTION:40A AT 50V PER MATED CONTACT(WHEN MATED WITH CUSTOMER SUPPLIED METAL BLADE OR BUS BAR).
6. INSULATION RESISTANCE: 5000 MEGOHMS AT APPLY 500 VDC BETWEEN ADJACENT TERMINALS OR GROUND.
7. TEPPERATURE
OPERATING:-40°C TO +105°C
8. PCB THICKNESS: 2.36MM MIN

RECOMMENDED TIN PLATEDTHOUGH HOLE DIMMENSIONS
COPPER PLATE THICKNESS: 0.03MIN.(PER SURFACE)
TIN PLATE THICKNESS: 0.0003MIN.(PER SURFACE)

RECOMMENDED EDGE CARD LAYOUT
EDGE CARD THICKNESS : 1.57±0.15mm
TOLERANCE:±0.05
Au PLATE THICKNESS: 0.000762 MIN.

20	POWER	POWER		
POS.	SEGMENT 1	SEGMENT 2	SEGMENT 3	NOTES

UNITS ■ mm □ INCH		NAME: POWER EDGE CONNECTOR POWER 20P. PRESS-FIT		 NEXTRONICS ENGINEERING CORP.		
GENERAL TOLERANCES: (UNLESS SPECIFIED)		PART NO: R-815F1132P2000				TITLE: CUSTOMER DWG.
	mm	INCH	APPD: Seawen 9/26,12		DWG NO: 010-0000-764	
4 PLACE	±***	±.***	CHKD: Ammie 9/26,12		C	
3 PLACE	±0.10	±.***	DRAWN: Jone 9/26,12		SCALE: SHEET: REV.:	
2 PLACE	±0.15	±.***			2:1 1/1 A	
1 PLACE	±0.25	±.***				
ANGULAR:	X°±2°	.X°±***				

A	ECN-210160	9/26,12	Seawen
X1	NEW DESIGN	9/20,12	Seawen
REV.	DESCRIPTION	DATE	APPD